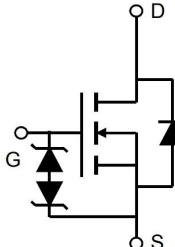


N-Channel Enhancement Mode Power MOSFET

<p>Description</p> <p>The GT011N03ME uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ● V_{DS} 30V ● I_D (at $V_{GS} = 10V$) 209A ● $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 1.6mΩ ● $R_{DS(ON)}$ (at $V_{GS} = 4.5V$) < 2.0mΩ ● 100% Avalanche Tested ● RoHS Compliant ● ESD (HBM)>8KV <p>Application</p> <ul style="list-style-type: none"> ● Power switch ● DC/DC converters 	 <p>Schematic diagram</p>  <p>TO-263</p>
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Ordering Information			
Device	Package	Marking	Packaging
GT011N03ME	TO-263	GT011N03	800pcs/Reel

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Continuous Drain Current	I_D	209	A
Pulsed Drain Current (note1)	I_{DM}	836	A
Gate-Source Voltage	V_{GS}	± 18	V
Power Dissipation	P_D	89	W
Single pulse avalanche energy (note2)	E_{AS}	361	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	°C

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	55	°C/W
Maximum Junction-to-Case	R_{thJC}	1.4	°C/W

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 18\text{V}$	--	--	± 50	uA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.0	1.7	2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$	--	1.28	1.6	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$	--	1.66	2.0	
Forward Transconductance	g_{FS}	$V_{\text{GS}} = 5\text{V}, I_D = 10\text{A}$	--	36	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 15\text{V}, f = 1.0\text{MHz}$	--	6140	--	pF
Output Capacitance	C_{oss}		--	2171	--	
Reverse Transfer Capacitance	C_{rss}		--	552	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 15\text{V}, I_D = 30\text{A}, V_{\text{GS}} = 10\text{V}$	--	98	--	nC
Gate-Source Charge	Q_{gs}		--	16	--	
Gate-Drain Charge	Q_{gd}		--	11	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 15\text{V}, I_D = 30\text{A}, R_G = 1.6\Omega$	--	13	--	ns
Turn-on Rise Time	t_r		--	7.5	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	51	--	
Turn-off Fall Time	t_f		--	8.6	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	209	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = 30\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	1.2	V
Reverse Recovery Charge	Q_{rr}	$I_F = 30\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A/us}$	--	112	--	nC
Reverse Recovery Time	T_{rr}		--	32	--	ns

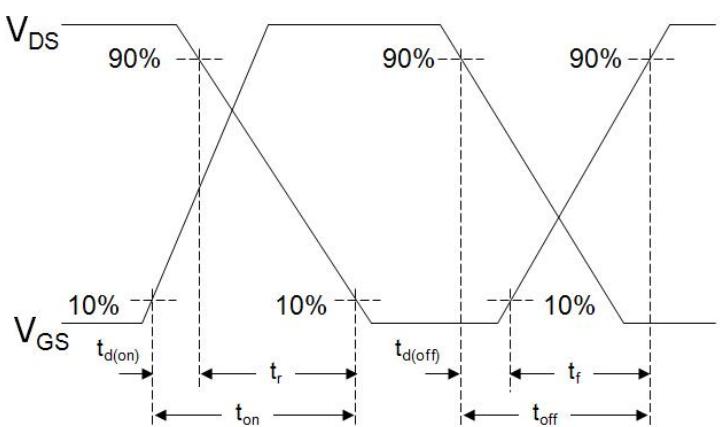
Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=30\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$
3. Identical low side and high side switch with identical R_G

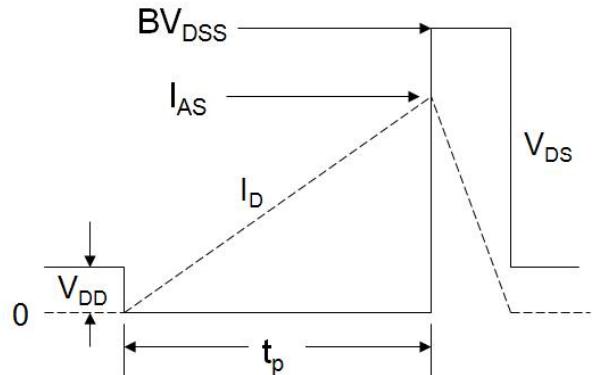
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

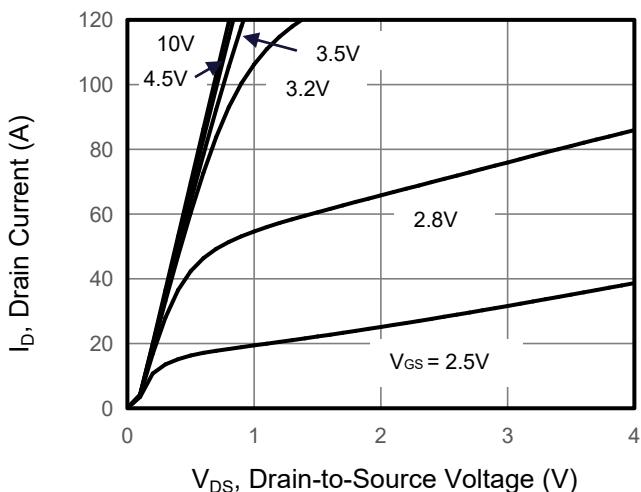


Figure 2. Transfer Characteristics

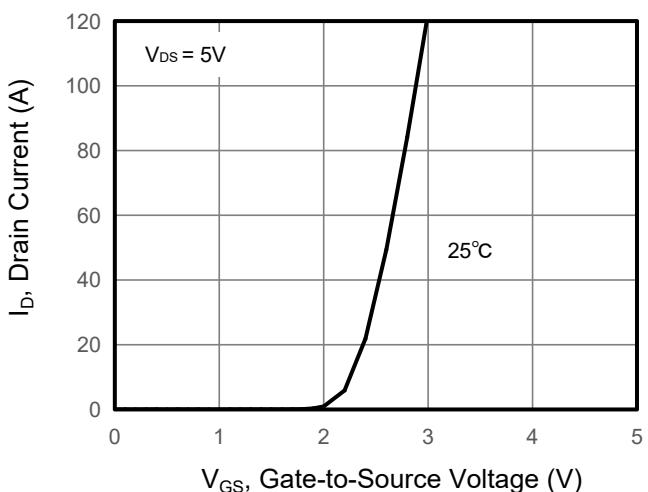


Figure 3. Drain Source On Resistance

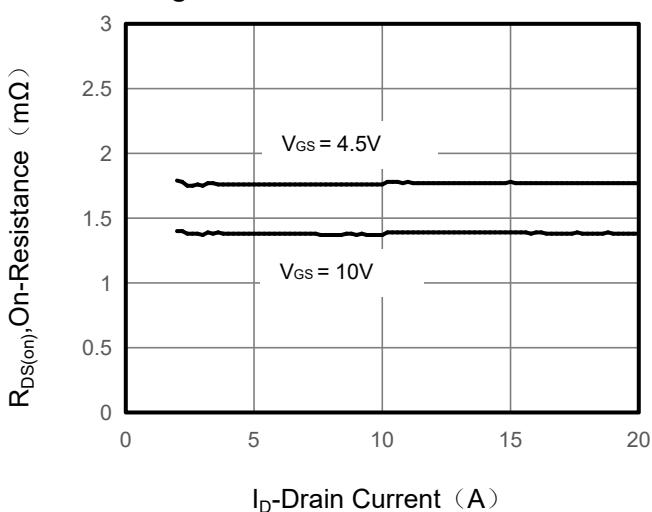


Figure 4. Gate Charge

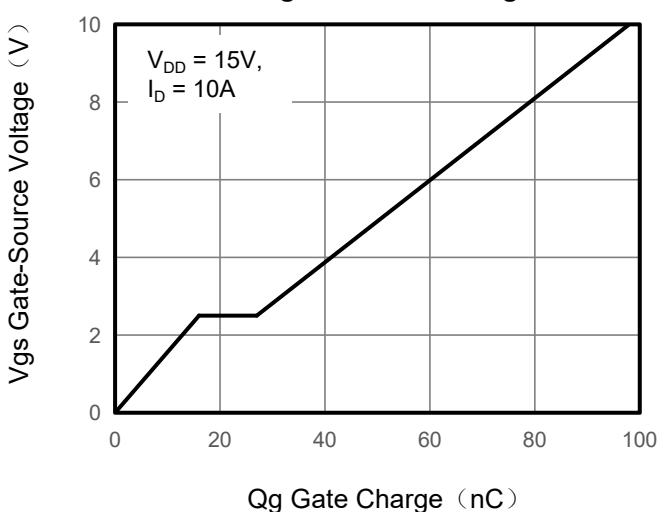


Figure 5. Capacitance

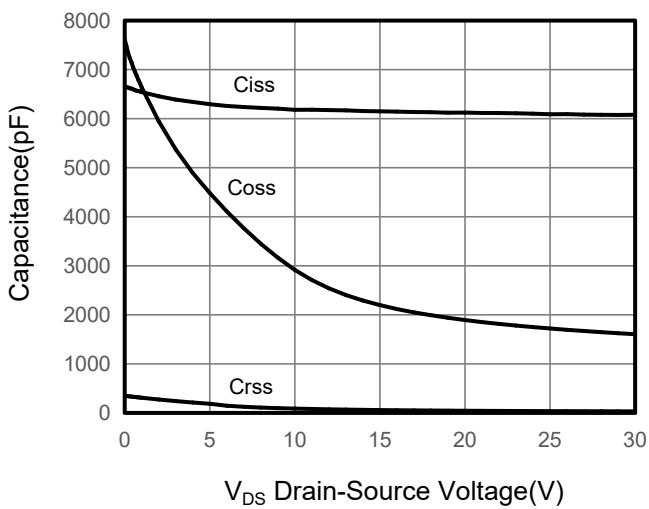
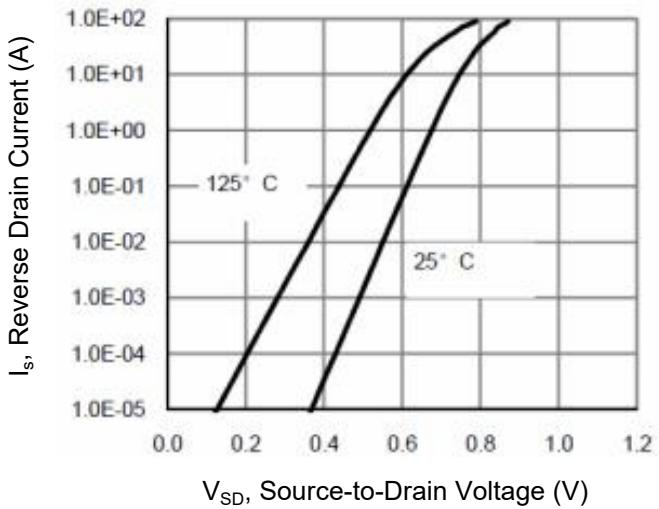


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

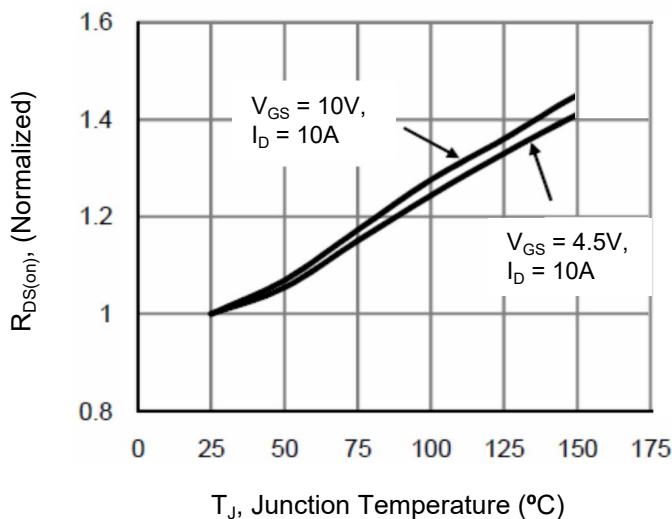


Figure 8. Safe Operation Area

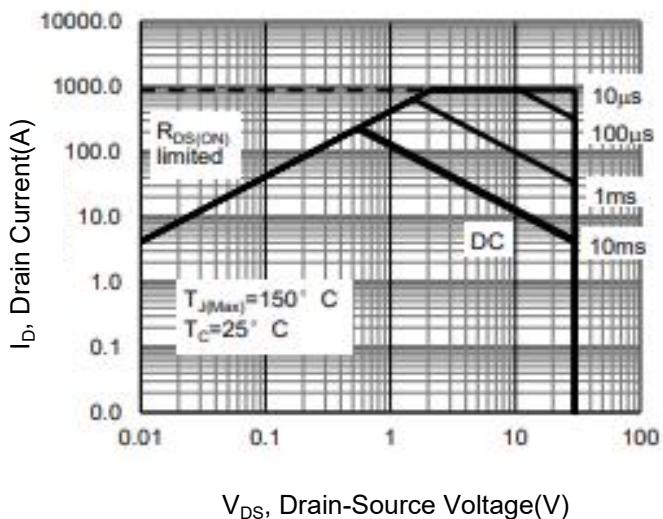
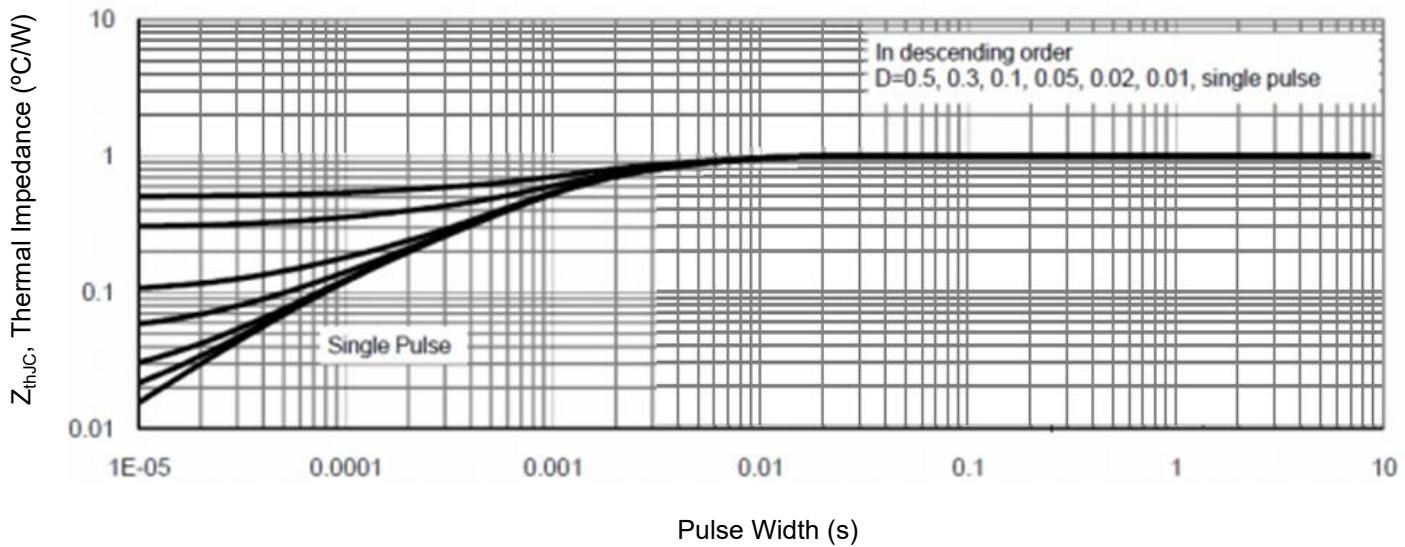
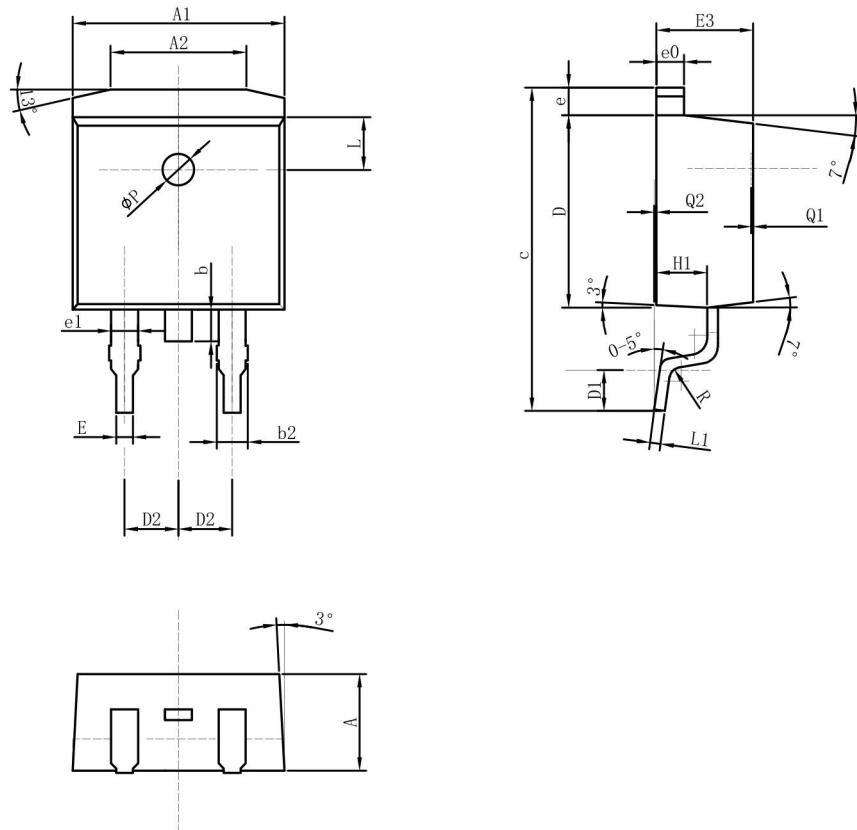


Figure 9. Normalized Maximum Transient Thermal Impedance



TO-263 Package Information



COMMON DIMENSIONS

SYMBO	mm		
	MIN	NOM	MAX
A	4.52	4.57	4.62
A1	9.95	10.00	10.05
A2	6.30	6.40	6.50
b	1.30	1.50	1.70
b2	1.17	1.27	1.37
c	14.80	15.00	15.20
D	9.05	9.10	9.15
D1	1.90	2.10	2.30
D2	—	2.54	—
E	—	0.80	—
E3	—	4.57	—
e	—	1.30	—
e0	—	1.30	—
e1	1.73	3	—
H1	—	2.40	—
L	—	2.50	—
L1	—	0.50	—
φP	—	1.50	—
R	—	0.50	—
Q1	0.10	—	0.15
Q2	0	—	0.02